

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L19	64	L18 and @pd>"20041214"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:46
L18	745	L17 and ((chamber or container or vessel) with (nozzle or orifice))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:46
L17	3113	L16 and ((rotat\$3 or rotary) with (hold\$3 or rotor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:46
L16	28434	(semiconductor or wafer or substrate) and ((chamber or container or vessel) with (cylindrical or cylinder))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:46
L15	5	((yuji near2 kamikawa).in. or (koji near2 egashira).in.) and @pd>"20041214"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:46
S46	18310	(tokyo and electron).as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:39
L14	10	8 and 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:39
L13	1155	(tokyo and electron).as. and @pd>"20041214"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:39
L12	21	8 and 11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:39

L11	246	(yuji near2 kamikawa).in. or (koji near2 egashira).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:39
L8	7829	((semiconductor or wafer or substrate)) and ((nozzle or orifice or spray\$3) with (fan or plane or planar))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:39
L10	15	(yuji near2 kamikawa).in. and (koji near2 egashira).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:38
S40	217	(yuji near2 kamikawa).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:34
L9	272	8 and rotor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:34
L7	2634	((semiconductor or wafer or substrate)) and ((nozzle and orifice or spray\$3) with (fan or plane or planar))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:34
L6	250	5 and rotor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:34
L5	6574	((semiconductor or wafer or substrate)) and ((nozzle or spray\$3) with (fan or plane or planar))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:34
S8	39	(134/198-200.ccls. and (semiconductor or wafer or substrate)) and ((nozzle or spray\$3) with (fan or plane or planar))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:33
L4	282	1 or 2 or 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:32

L3	57	156/345.21,345.51,345.54,345.55.ccls. and @pd>"20041214"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 13:32
L2	57	216/2,92.ccls. and @pd>"20041214"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 12:22
L1	170	134/198,199,200,902.ccls. and @pd>"20041214"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 12:22
S26	4048	134/198,199,200,902.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 12:21